

SAC305 - WATER SOLUBLE FLUX-CORE SOLDER WIRE**Product Description**

SRA solder wire is made from 100% virgin materials to the highest quality standards, right here in the USA. Our line of SAC305 alloy wire with a no-clean, water-soluble flux-core has been specifically designed for lead and lead-free applications.

It has improved activity over other no-clean solder wire for fast wetting action. This product leaves a clear residue after soldering and is shown to have no spattering.

Key Features

- Made in USA from 100% virgin materials
- Excellent quality general purpose solder
- No-clean, water soluble flux core
- For use on circuit boards
- Melts at 430°F (221°C)
- Contains 96.5% Sn, 3% Ag, 0.5% Cu
- Available in .020" and .031" gauge wire

Available Sizes**Wire Gauge: 0.020"**

- 4oz - WBWSSAC20-4OZ
- 1Lb - WBWSSAC20-1LB

Wire Gauge: 0.031"

- 2oz - WBWSSAC31-2OZ
- 4oz - WBWSSAC31-4OZ
- 1Lb - WBWSSAC31-1LB



Test Result	Specification	Test Method
Color & Appearance	Light yellow opaque solid	Visual
Halide Content	Pass	
Copper Mirror	No removal of copper film	IPC-TM-650 2.3.32
Flux Classification	RELO	J-STD-004
Silver Chromate	Pass	IPC-TM-650 2.3.33
Corrosion	Pass	IPC-TM-650 2.6.15
Flux Residue Dryness	Pass	IPC-TM-650 2.4.47
Spitting of Flux-Cored Solder	0.20%	IPC-TM-650 2.4.48
Solder Spread	120 mm ²	IPC-TM-650 2.4.46

Safety:

See the Safety Data Sheet for safety procedures.

Storage & Shelf Life:

Wire Solder should be stored in a dry environment away from direct heat. We recommend Using gloves when handling solder wire directly. Solder wire has 2 years shelf life.

Disposal:

Dispose of in accordance with all local state and federal regulations.

The information contained herein is based on technical data that we believe to be reliable and is intended for use by persons having technical skill, at their own risk. Users of our products should make their own tests to determine the suitability of each product for their particular process. SRA Soldering Products will assume no liability for results obtained or damages incurred through the application of the data presented.

